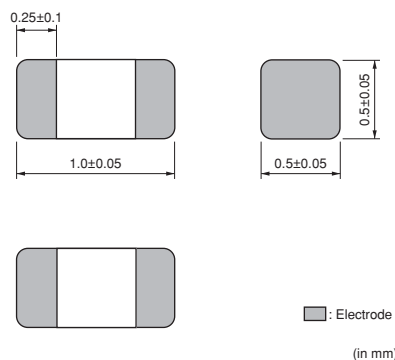


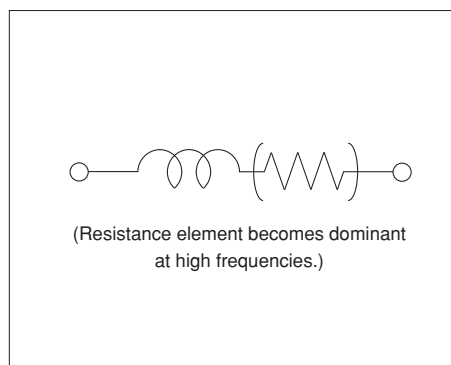
EMIFIL® (Inductor type) Chip Ferrite Bead for GHz Noise

BLM15H Series (0402 Size)

■ Dimensions



■ Equivalent Circuit



■ Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	10000
J	330mm Paper Tape	50000
B	Bulk(Bag)	1000

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance	Operating Temperature Range
BLM15HG601SN1□	600ohm ±25%	1000ohm ±40%	300mA	0.7ohm max.	-55 to +125°C
BLM15HG102SN1□	1000ohm ±25%	1400ohm ±40%	250mA	1.1ohm max.	-55 to +125°C
BLM15HD601SN1□	600ohm ±25%	1400ohm ±40%	300mA	0.85ohm max.	-55 to +125°C
BLM15HD102SN1□	1000ohm ±25%	2000ohm ±40%	250mA	1.25ohm max.	-55 to +125°C
BLM15HD182SN1□	1800ohm ±25%	2700ohm ±40%	200mA	2.2ohm max.	-55 to +125°C
BLM15HB121SN1□	120ohm ±25%	500ohm ±40%	300mA	0.7ohm max.	-55 to +125°C
BLM15HB221SN1□	220ohm ±25%	900ohm ±40%	250mA	1.0ohm max.	-55 to +125°C

Number of Circuits: 1

Continued on the following page.

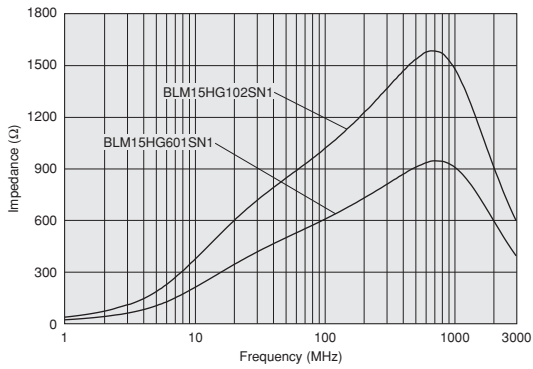
● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

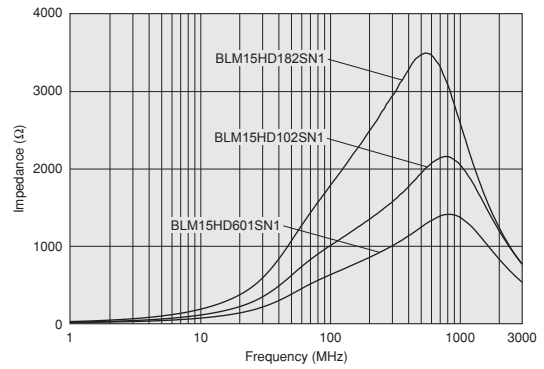
- This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Continued from the preceding page.

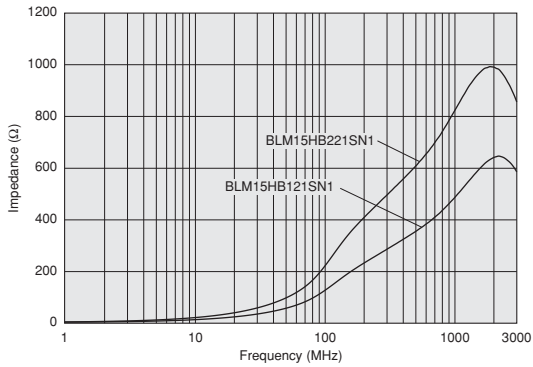
Impedance-Frequency Characteristics (Main Items)
BLM15HG Series



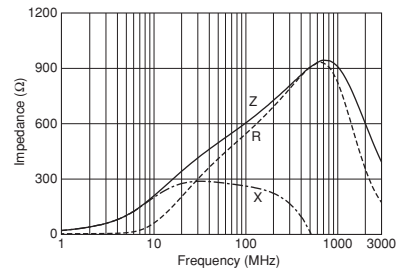
Impedance-Frequency Characteristics (Main Items)
BLM15HD Series



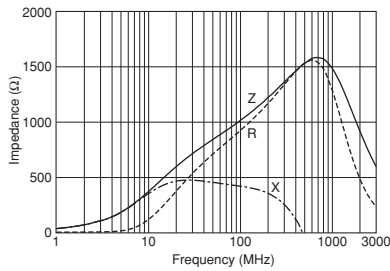
Impedance-Frequency Characteristics (Main Items)
BLM15HB Series



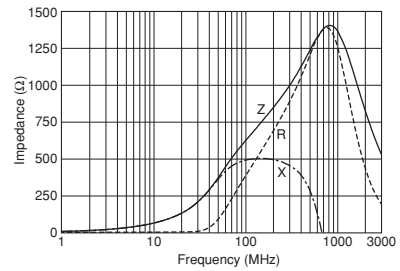
Impedance-Frequency Characteristics
BLM15HG601SN1



Impedance-Frequency Characteristics
BLM15HG102SN1



Impedance-Frequency Characteristics
BLM15HD601SN1



Continued on the following page.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

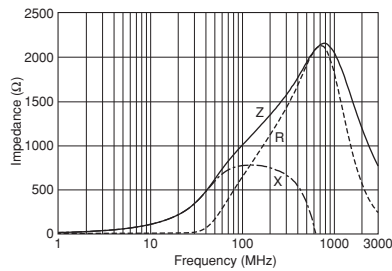
Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
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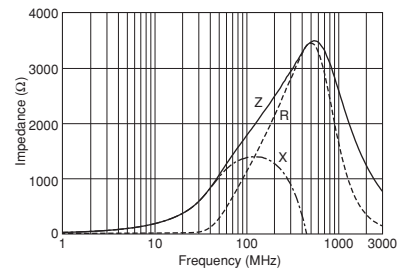
Impedance-Frequency Characteristics

BLM15HD102SN1



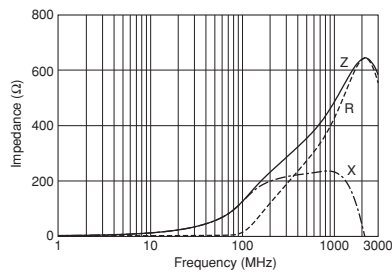
Impedance-Frequency Characteristics

BLM15HD182SN1



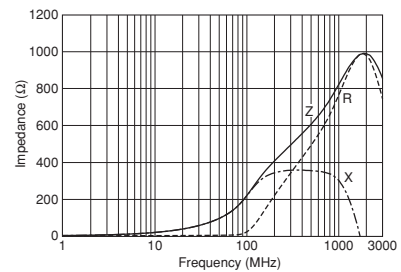
Impedance-Frequency Characteristics

BLM15HB121SN1



Impedance-Frequency Characteristics

BLM15HB221SN1



Caution/Notice

Caution (Rating)

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

Note:

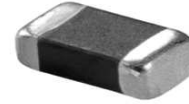
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- This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Chip Bead For GHz noise suppression

CIV05 Series (1005/ EIA 0402)

APPLICATION

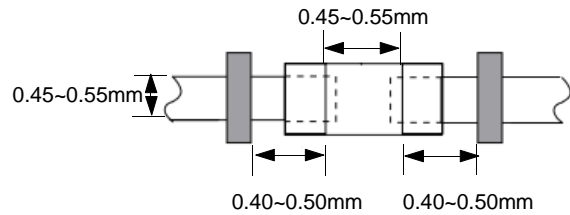
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.



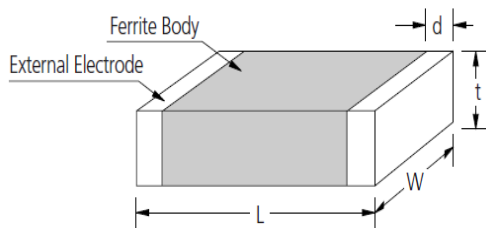
FEATURES

- CIV Series have high impedance in a GHz band and suppress GHz noise which is usually made due to high frequency of the electronic appliances, high speed and mass storage of the data.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



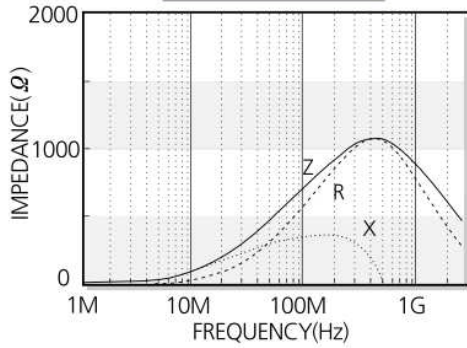
Type	Dimension [mm]			
	L	W	t	d
05	1.0±0.05	0.5±0.05	0.5±0.05	0.25±0.1

DESCRIPTION

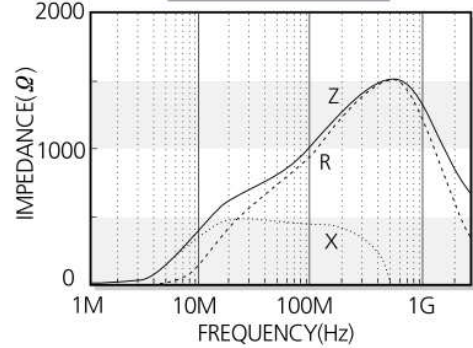
Part no.	Impedance (Ω)±25%@100MHz	Impedance (Ω)±40%@1GHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIV05U601	600	1000	0.7	300
CIV05U102	1000	1400	1.1	250
CIV05J102	1000	2000	1.25	250
CIV05J182	1800	2700	2.20	200

CHARACTERISTIC DATA

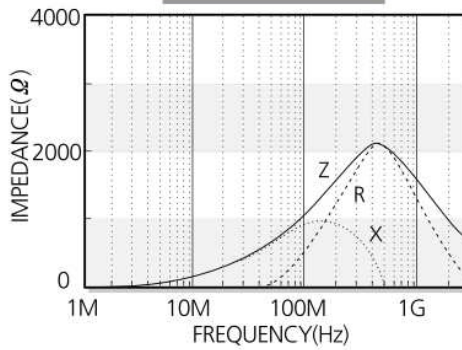
CIV05U601NC



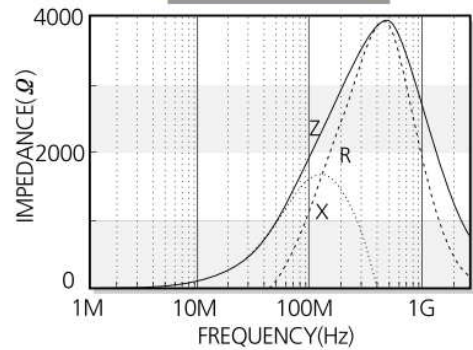
CIV05U102NC



CIV05J102NC



CIV05J182NC



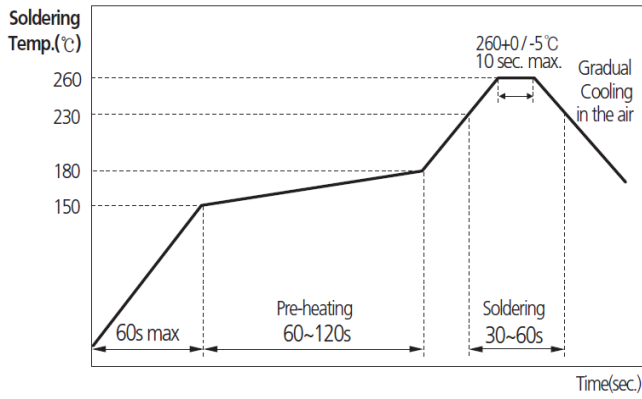
PRODUCT IDENTIFICATION

CI V 05 U 102 N C
(1) (2) (3) (4) (5) (6) (7)

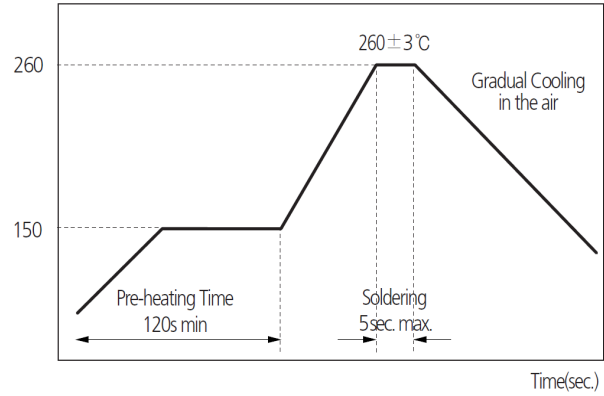
- (1) Chip Beads
- (2) Multi-layer type for GHz Noies suppression
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (601:600Ω, 102:1000Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000



Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.